

**Notice of References Cited**

Application/Control No.

10/598,124

Applicant(s)/Patent Under  
Reexamination  
SAKAMOTO ET AL.

Examiner

YOSHITOSHI TAKEUCHI

Art Unit

1726

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*	B	US-3,359,132	12-1967	WITTMANN ALBIN E	228/125
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	M	US-			

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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	V	Niedzielski, Neopentyl Polyol Ester Lubricants—Bulk Property Optimization, 54-58 Ind. Eng. Chem., Prod. Res. Dev. 15 (1976)
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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